


MATERIAL DECLARATION SHEET



Package Type	PTVS1-(043C-058C)-H			
Product Line	Semiconductor Products			
Compliance Date	10 th March 2022			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.1953	Amorphous Silica	60676-86-0	87.000	55.13735	57.14
				Solid Epoxy Resin 1	Proprietary	4.600	0.18586	
				Solid Epoxy Resin 2	Proprietary	4.490	0.15846	
				Phenol Resin	Proprietary	2.700	0.93506	
				Carbon Black	1333-86-4	0.700	0.34343	
				Crystalline Silica	14808-60-7	0.510	0.38268	
2	Leadframe	Copper Alloy	0.0618	Copper	7440-50-8	97.433	17.68351	18.08
				Iron	7439-89-6	2.350	0.37482	
				Phosphorus	7723-14-0	0.125	0.00592	
				Zinc	7440-66-6	0.082	0.01193	
				Lead	7439-92-1	0.010	0.00230	
3	Clip	Copper Alloy	0.0340	Copper	7440-50-8	95.485	9.40222	9.95
				Silver	7440-22-4	4.500	0.54400	
				Iron	7439-89-6	0.005	0.00043	
				Lead	7439-92-1	0.005	0.00062	
				Zinc	7440-66-6	0.003	0.00024	
				Phosphorous	7723-14-0	0.002	0.00005	
4	Electrodes	Copper Alloy	0.0203	Copper	7440-50-8	95.485	5.61358	5.94
				Silver	7440-22-4	4.500	0.32479	
				Iron	7439-89-6	0.005	0.00026	
				Lead	7439-92-1	0.005	0.00037	
				Zinc	7440-66-6	0.003	0.00014	
				Phosphorous	7723-14-0	0.002	0.00003	
5	Chip	Silicon	0.0183	Silicon	7440-21-3	90.650	4.90814	5.35
				Nickel	7440-02-0	5.403	0.19010	
				Aluminum	7429-90-5	3.815	0.24483	
				Gold	7440-57-5	0.132	0.00606	
6	Solder Paste	Solder	0.0093	Lead*	7439-92-1	92.500	2.55418	2.71
				Tin	7440-31-5	5.000	0.08802	
				Silver	7440-22-4	2.500	0.06632	
7	Terminal Finish	Tin	0.0028	Tin	7440-31-5	100.000	0.8343	0.83
		Total weight	0.3418					

* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)